

ABSTRACT

A semiconductor device includes: a semiconductor chip having a plurality of pads formed on the main surface thereof; chip components having connection terminals formed on both ends thereof; a module board on which the semiconductor chip and the chip components are mounted; solder connection portions for connecting the chip components to the terminals of the module board and connecting the semiconductor chip to the module board by solder; gold wires for connecting pads of the semiconductor chip to terminals of the module board corresponding thereto; and a sealing section which covers the semiconductor chip, the chip components, solder connection portions and gold wires and is formed of an insulating elastic resin such as silicone resin, wherein the wire height is set to 0.2 mm or less and the wire length is set to 1.5 mm or less so as to prevent the gold wires from being broken.